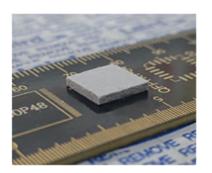


Tflex[™] HD7.5 Series Thermal Gap Filler Preliminary Data Sheet



PRODUCT DESCRIPTION

Tflex[™] HD7.5 gap filler is a very soft silicone material in our high deflection series. With a thermal conductivity of 7.5W/ mk, Tflex[™] HD7.5 is designed to provide superior pressure versus deflection characteristics. The material will provide minimal stress on components during application while maintaining low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

Tflex[™] HD7.5 gap filler is available in thickness from 1mm (0.040") to 5mm (0.200"). Laird can provide material to meet your production needs in any region through our local production facilities. Please contact your local Laird sales or field engineering contact for samples or questions.

FEATURES AND BENEFITS

- 7.5 W/mK thermal conductivity
- Low pressure versus deflection
- Minimizes board and component stress
- Low Outgassing and oil bleeding
- Large tolerance applications

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	1mm (0.40") - 5mm (0.200")	N/A
Thermal Conductivity (W/mK)	7.5	Hot Disk
	7.8	ASTMD5470
Density (g/cc)	3.4	Helium Pycnometer
Hardness Shore 00 (3 sec)	15	ASTM D2240
Hardness Shore 000 (3 sec)	60	ASTM D2240
Outgassing TML (weight %)	TBD	ASTM E595
Outgassing CVCM (weight %)	TBD	ASTM E595
Temperature Range	-40°C to 150°C	Laird Test Method
Rth at 1mm, 10 psi	0.119°C-in2/W	ASTM D5470
Dielectric Constant at 1 MHz	TBD	ASTM D150
UL Flammability Rating	V-0 (pending)	UL 94
Volume Resistivity	1.1X10 ¹⁴ Ω.cm	ASTM D257

*Preliminary release, all data subject to change

THR-DS-Tflex[™] HD7.5 051622

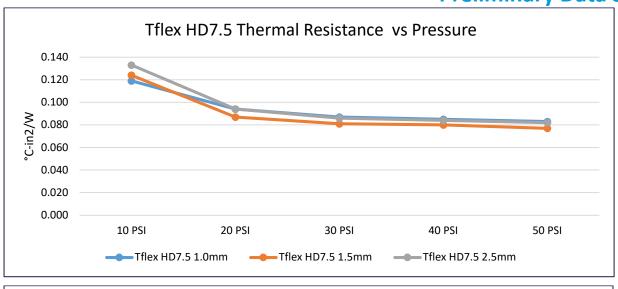
USA: +1.866.928.8181 Europe: +49.8031.24600 Asia: +86.755.2714.1166

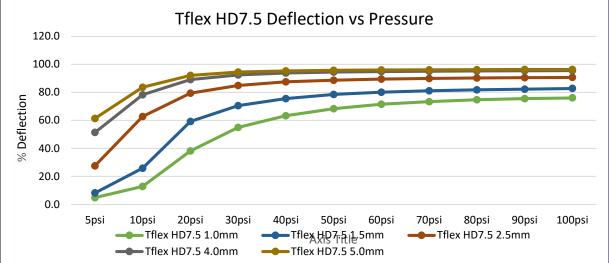
www.laird.com

Any information furnished by Laird Technologies, Inc. or any of its affiliates or agents ("Laird") is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird materials rests with the end user. Laird makes no warranties as to the fitness, merchantability, suitability or non-infringement of any Laird materials or products for any specific or general uses. Laird shall not be liable for incidental or consequential damages of any kind. All Laird products are sold pursuant to the Laird's Ferms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2022 Laird Technologies, Inc. All Rights Reserved. Laird", Laird Technologies¹⁰, the Laird Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. DuPont¹⁰ is a trademark or registered trademark of DuPont de Nemours, Inc. or an affiliate company thereof. Other marks may be owned by third parties. Nothing herein provides a license under any Laird or any Laird or any tride.



Tflex[™] HD7.5 Series Thermal Gap Filler Preliminary Data Sheet





AVAILABILITY

STANDARD THICKNESSES

- 1 mm (0.040") up to 5 mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts.

OPTIONS

- DC1 Eliminate tack from one side
- A1 Adhesive on one side

PART NUMBER SYSTEM

Tflex[™] indicates Laird elastomeric thermal gap filler product line. HD7.5 indicates high deflection 7.5 W/mk material. Thickness of sheet in mm is listed after material name.

EXAMPLES:

- Tflex[™] HD7.5,1.00 =1.00mm thick for Tflex[™] HD7.5 material
- Tflex[™] HD7.5,1.00,A1 =1.00mm thick for Tflex[™] HD7.5 material with adhesive on one side

THR-DS-Tflex HD7.5 Data Sheet 05162022

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user. Laird Technologies makes no warranties as to the fitness, merchantability, suitability or non- infringement of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies, the Laird Technologies 'Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2013 Laird Technologies, Inc. All Rights Reserved. Laird Technologies, the Laird Technologies Logo, and other marks are trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.